

DaVinci™ EVM System Board Modifications Required to Ensure Proper Operation of TNETW1350A-Based WLSs

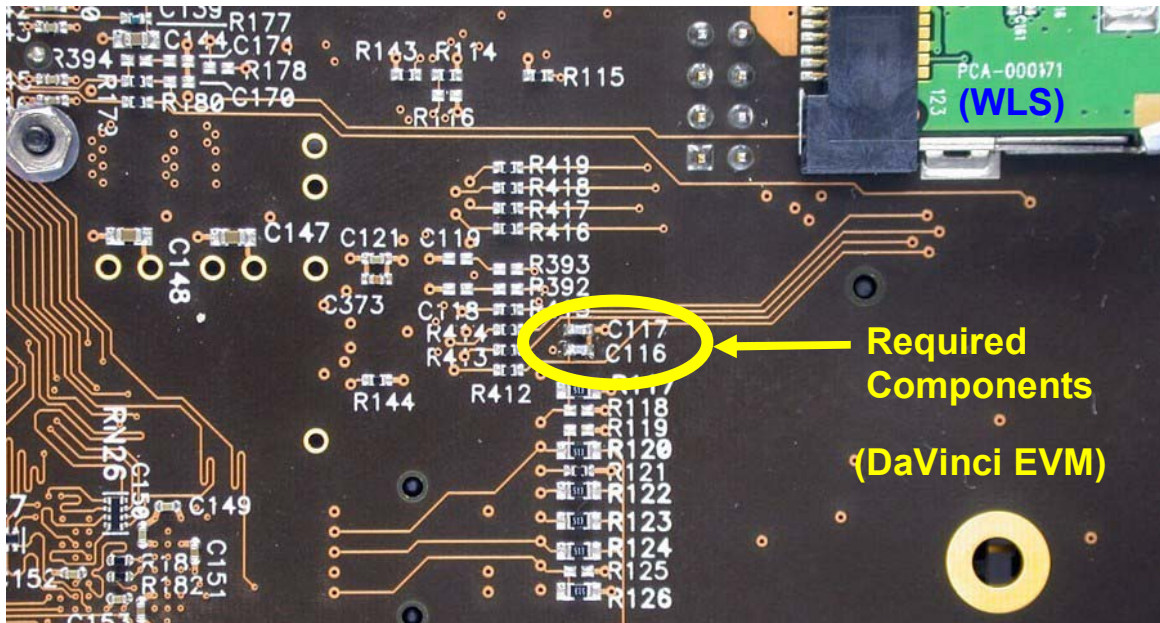
Applications Engineering

Wireless LAN

To ensure proper operation of TNETW1350A-based WLAN subsystems (WLSs), the following modifications are required for DaVinci™ EVM system board revisions beta, gamma, and delta.

Modifications:

1. To ensure the proper operation of the VLYNQ™ interface: Change capacitors C116 and C117 from “no-stuff” to 5.6 pF, C0G, 0402, +/- 0.25 pF, 50 V. See the figure below for the location of these components (bottom side near the MiniPCI connector).



2. To ensure that +5 V dc is supplied via the MiniPCI connector pins 97 and 103: Remove ferrite bead L58 and install it at location L59, which is currently not loaded on the board. Both L58 and L59 are located on the top side of the DaVinci EVM board above the MiniPCI connector.

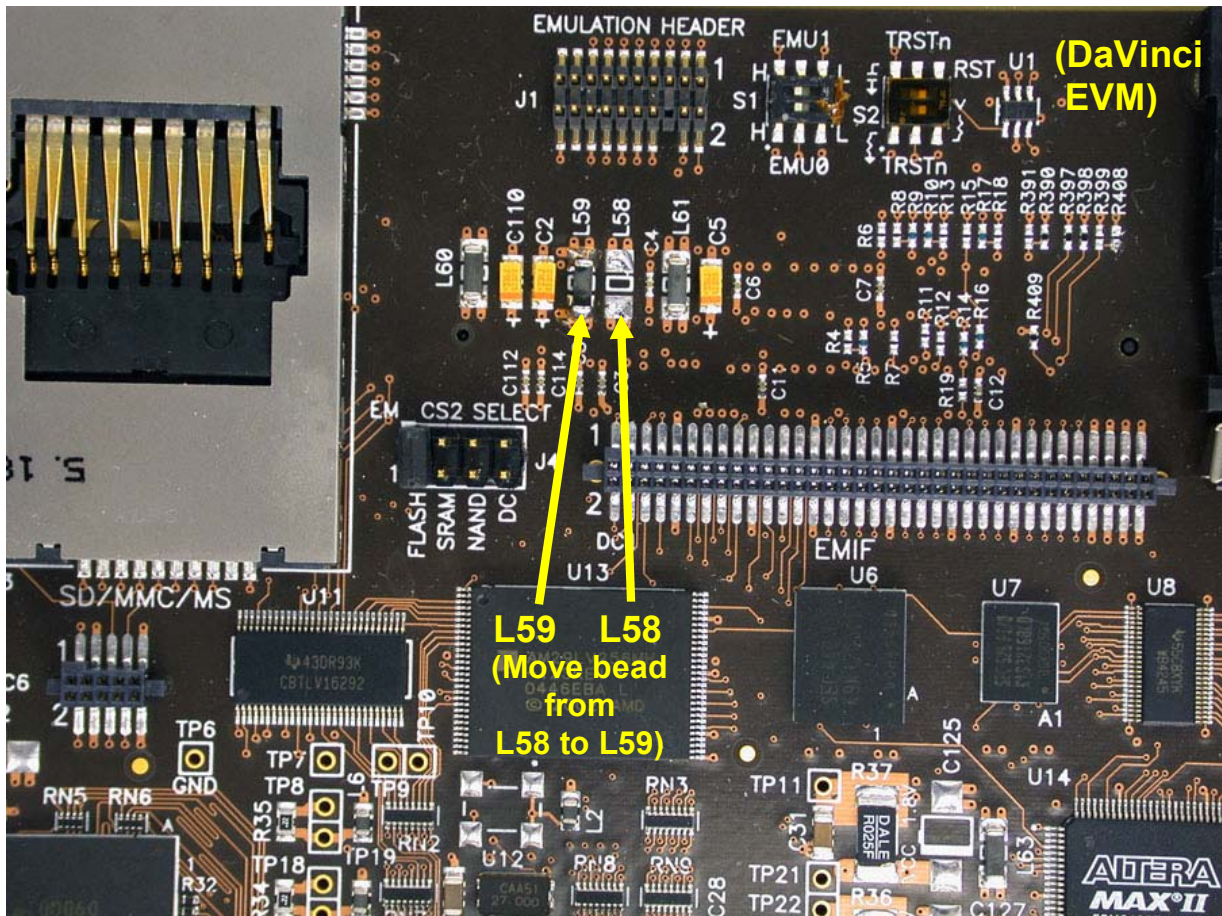


Table 1. Revision History

Revision	Date	Comments
1.1	03/13/2006	JU: Added modification number 2.
1.0	12/20/2005	JU: First release.

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